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VIA FAX & REGISTERED POST

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IPEA/AU

Attention: I.A. Barrett  
Australian Patent Office  
PO Box 200,  
Woden ACT 2606  
Australia

Dear Madam/Sir

RE: Response to Written Opinion for PCT Patent Appl. No. **PCT/SG2003/000204**  
Applicant : Advanced Systems Automation Ltd.  
Title: Handler For Semiconductor Singulation And Method Therefor  
Our Ref : 1007.P056PCT/KJT/ayu

This is a response to the outstanding Written Opinion with a mailing date of August 11, 2004, for the above-identified PCT patent application. Enclosed please find one (1) page of the Response to Written Opinion, a clean copy of claims 1-30 and a markup copy of claims 1-30.

We look forward to receiving affirmation that claims 1-30 are fully supported by the Description of the patent application.

Yours sincerely

**LAWRENCE Y.D. HO & ASSOCIATES PTE LTD**



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Encl.

10/533236

International Application PCT/SG2003/000204

Attorney's ref. 1007.P056PCT

Title: Handler For Semiconductor Singulation And Method Therefor

JC17 Rec'd PCT/PTO 29 APR 2005

**Response to Written Opinion**

This is a response to the outstanding Written Opinion with a mailing date of August 11, 2004 for the International Application No. PCT/2003/000204.

There are thirty (30) claims pending in this patent application: claims 4-16, and 18-30 unchanged; claims 1-3 and 17 replaced by amended claims bearing the same number.

Applicants gratefully note that the Examiner has concluded that claims 1-30 satisfy the three requirements under the PCT rules. However, the Examiner still maintains that claims 1-30 are not fully supported by the description because the claims are not limited to water jet singulation. While Applicants strongly disagree with the Examiner's conclusions, for the sake of putting the claims in better forms for the IPER, Applicants have amended claims 1 and 17 to specify that the singulation employ a water jet. In accordance with the amended made to claim 1, claims 2 and 3 have also been amended to be in line with claim 1. A markup copy showing the changes made and a replacement copy are attached hereinwith. The amendments are supported by the filed patent application. No new matter has been introduced by the amendments.

In view of the amendments submitted hereinwith, Applicants respectfully submit that claims 1-30 are fully supported by the description.

## Claims

1. A handler for singulating at least one packaged substrate into a plurality of packaged semiconductor devices by using a water jet, the handler comprising:

a first movable mount for moving between a loading location and a cutting location, the first movable mount adapted to receive the at least one packaged substrate at the loading location, the first movable mount for transporting the at least one packaged substrate from the loading location to the cutting location, and the first movable mount adapted to secure the at least one packaged substrate thereon while the at least one packaged substrate is at least partially cut at the cutting location; and

a second movable mount for moving between the cutting location and an unloading location, the second movable mount adapted to receive the at least one packaged substrate that is at least partially cut at the cutting location, the second movable mount for securing the at least one packaged substrate thereon while the at least one packaged substrate is at least partially cut at the cutting location to produce at least some of the plurality of packaged semiconductor devices, and the second movable mount for transporting the at least some of the plurality of packaged semiconductor devices from the cutting location to the unloading location.

2. A handler in accordance with claim 1, further comprising at least one water jet as the cutting tool disposed at the cutting location, the at least one cutting tool suitably adapted for cutting the at least one packaged substrate.

3. A handler in accordance with claim 2, wherein the ~~at least one cutting tool comprises~~ at least one water jet is from at least one water jet nozzle.

4. A handler in accordance with claim 3, wherein the at least one water jet includes abrasive material.
5. A handler in accordance with claim 4, further comprising a distance detector mounted proximal the at least one water jet nozzle, the distance detector for detecting the distance between the at least one water jet nozzle and the at least one packaged substrate when cutting the at least one packaged substrate with the at least one water jet, and the distance detector for providing a detected distance.
6. A handler in accordance with claim 5 further comprising a movable mount for mounting the water jet thereto, the movable mount being coupled to receive an adjusted distance, the movable mount for maintaining a predetermined distance between the water jet and the at least one packaged substrate when cutting the at least one packaged substrate with the water jet, in accordance with the adjusted distance.
7. A handler in accordance with claim 1 further comprising at least one transport guide that extends from the loading location, through the cutting location, and to the unloading section, wherein at least the first movable mount is movably coupled to the at least one transport guide.
8. A handler in accordance with claim 7 wherein the at least one transport guide comprises at least a pair of rails, and wherein at least the first movable mount is movably coupled to the pair of rails.
9. A handler in accordance with claim 8 wherein at least the second movable mount is movably coupled to the pair of rails.

10. A handler in accordance with claim 9 wherein the pair of rails are substantially linear and extend substantially parallel to each other from the loading location, through the cutting location, and to the unloading location.
11. A handler in accordance with claim 1 wherein the first movable mount comprises a rotatable vacuum chuck for securing the at least one packaged substrate thereto.
12. A handler in accordance with claim 11 wherein the second movable mount comprises a rotatable vacuum chuck for securing the at least one packaged substrate thereto.
13. A handler in accordance with claim 1, further comprising a movably mounted image capture device directed at the loading location for capturing at least one image of the at least one packaged substrate on the first movable mount, when the first movable mount is at the loading location.
14. A handler in accordance with claim 1, further comprising a second image capture device directed at the cutting location for capturing at least one image of the at least one packaged substrate on the second movable mount, when the second movable mount is at the cutting location.
15. A handler in accordance with claim 1, further comprising a transfer means for transferring the at least one packaged substrate from the first moveable mount to the second movable mount.
16. A handler in accordance with claim 1, wherein the transfer means comprises at least one pick and place assembly mounted to operate at the cutting location.

17. A method for handling at least one packaged substrate for singulation into a plurality of packaged semiconductor devices by using a water jet, the method comprising:

a) providing:

a first movable mount for moving between a loading location and a cutting location; and

a second movable mount for moving between the cutting location and an unloading location,

b) moving the first movable mount from the loading location to the cutting location with the at least one packaged substrate disposed thereon;

c) cutting the at least one packaged substrate in a first reference direction at the cutting location;

d) transferring the at least one packaged substrate from the first movable mount to the second movable mount;

e) cutting the at least one packaged substrate in a second reference direction, different from the first reference direction, at the cutting location, to produce the plurality of packaged semiconductor devices; and

f) moving the second movable mount from the cutting location to the unloading location.

18. A method in accordance with claim 17 further comprising, prior to (b), loading the at least one packaged substrate on the first movable mount.

19. A method in accordance with claim 17 further comprising, after (f), unloading the plurality of packaged semiconductor devices on the second movable mount.

20. A method in accordance with claim 17, wherein step (a) further comprises providing a water jet for cutting the at least one packaged substrate in (c).
21. A method in accordance with claim 17, wherein (a) further comprises providing a water jet for cutting the at least one packaged substrate in (e).
22. A method in accordance with claim 21 further comprising, after (b) but before (c), aligning the at least one packaged substrate with the water jet.
23. A method in accordance with claim 21 further comprising, after (d) but before (e), aligning the at least one packaged substrate with the water jet.
24. A method in accordance with claim 17 wherein (b) further comprises moving the second movable mount from the cutting location to the unloading location with at least another previously singulated packaged substrate disposed thereon.
25. A method in accordance with claim 24 wherein (c) further comprises unloading the at least another previously singulated packaged substrate at the unloading location.
26. A method in accordance with claim 20 wherein (c) further comprises moving the first movable mount in the first reference direction.
27. A method in accordance with claim 20 wherein (c) further comprises moving the water jet in the second reference direction.

28. A method in accordance with claim 21 wherein (e) further comprises moving the second movable mount in the first reference direction.

29. A method in accordance with claim 21 wherein (e) further comprises moving the water jet in the second reference direction.

30. A method in accordance with claim 17, wherein (d) comprises picking the at least one packaged substrate off the first movable mount, moving the first movable mount from the cutting location to the loading location, moving the second movable mount from the unloading location to the cutting location, and placing the at least one packaged substrate on the second movable mount.

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## Claims

1. A handler for singulating at least one packaged substrate into a plurality of packaged semiconductor devices by using a water jet, the handler comprising:

a first movable mount for moving between a loading location and a cutting location, the first movable mount adapted to receive the at least one packaged substrate at the loading location, the first movable mount for transporting the at least one packaged substrate from the loading location to the cutting location, and the first movable mount adapted to secure the at least one packaged substrate thereon while the at least one packaged substrate is at least partially cut at the cutting location; and

a second movable mount for moving between the cutting location and an unloading location, the second movable mount adapted to receive the at least one packaged substrate that is at least partially cut at the cutting location, the second movable mount for securing the at least one packaged substrate thereon while the at least one packaged substrate is at least partially cut at the cutting location to produce at least some of the plurality of packaged semiconductor devices, and the second movable mount for transporting the at least some of the plurality of packaged semiconductor devices from the cutting location to the unloading location.

2. A handler in accordance with claim 1, further comprising at least one water jet as the cutting tool disposed at the cutting location, the at least one cutting tool suitably adapted for cutting the at least one packaged substrate.

3. A handler in accordance with claim 2, wherein the at least one water jet is from at least one water jet nozzle.

4. A handler in accordance with claim 3, wherein the at least one water jet includes abrasive material.
5. A handler in accordance with claim 4, further comprising a distance detector mounted proximal the at least one water jet nozzle, the distance detector for detecting the distance between the at least one water jet nozzle and the at least one packaged substrate when cutting the at least one packaged substrate with the at least one water jet, and the distance detector for providing a detected distance.
6. A handler in accordance with claim 5 further comprising a movable mount for mounting the water jet thereto, the movable mount being coupled to receive an adjusted distance, the movable mount for maintaining a predetermined distance between the water jet and the at least one packaged substrate when cutting the at least one packaged substrate with the water jet, in accordance with the adjusted distance.
7. A handler in accordance with claim 1 further comprising at least one transport guide that extends from the loading location, through the cutting location, and to the unloading section, wherein at least the first movable mount is movably coupled to the at least one transport guide.
8. A handler in accordance with claim 7 wherein the at least one transport guide comprises at least a pair of rails, and wherein at least the first movable mount is movably coupled to the pair of rails.
9. A handler in accordance with claim 8 wherein at least the second movable mount is movably coupled to the pair of rails.

10. A handler in accordance with claim 9 wherein the pair of rails are substantially linear and extend substantially parallel to each other from the loading location, through the cutting location, and to the unloading location.
11. A handler in accordance with claim 1 wherein the first movable mount comprises a rotatable vacuum chuck for securing the at least one packaged substrate thereto.
12. A handler in accordance with claim 11 wherein the second movable mount comprises a rotatable vacuum chuck for securing the at least one packaged substrate thereto.
13. A handler in accordance with claim 1, further comprising a movably mounted image capture device directed at the loading location for capturing at least one image of the at least one packaged substrate on the first movable mount, when the first movable mount is at the loading location.
14. A handler in accordance with claim 1, further comprising a second image capture device directed at the cutting location for capturing at least one image of the at least one packaged substrate on the second movable mount, when the second movable mount is at the cutting location.
15. A handler in accordance with claim 1, further comprising a transfer means for transferring the at least one packaged substrate from the first moveable mount to the second movable mount.
16. A handler in accordance with claim 1, wherein the transfer means comprises at least one pick and place assembly mounted to operate at the cutting location.

17. A method for handling at least one packaged substrate for singulation into a plurality of packaged semiconductor devices by using a water jet, the method comprising:

a) providing:

a first movable mount for moving between a loading location and a cutting location; and

a second movable mount for moving between the cutting location and an unloading location,

b) moving the first movable mount from the loading location to the cutting location with the at least one packaged substrate disposed thereon;

c) cutting the at least one packaged substrate in a first reference direction at the cutting location;

d) transferring the at least one packaged substrate from the first movable mount to the second movable mount;

e) cutting the at least one packaged substrate in a second reference direction, different from the first reference direction, at the cutting location, to produce the plurality of packaged semiconductor devices; and

f) moving the second movable mount from the cutting location to the unloading location.

18. A method in accordance with claim 17 further comprising, prior to (b), loading the at least one packaged substrate on the first movable mount.

19. A method in accordance with claim 17 further comprising, after (f), unloading the plurality of packaged semiconductor devices on the second movable mount.

20. A method in accordance with claim 17, wherein step (a) further comprises providing a water jet for cutting the at least one packaged substrate in (c).
21. A method in accordance with claim 17, wherein (a) further comprises providing a water jet for cutting the at least one packaged substrate in (e).
22. A method in accordance with claim 21 further comprising, after (b) but before (c), aligning the at least one packaged substrate with the water jet.
23. A method in accordance with claim 21 further comprising, after (d) but before (e), aligning the at least one packaged substrate with the water jet.
24. A method in accordance with claim 17 wherein (b) further comprises moving the second movable mount from the cutting location to the unloading location with at least another previously singulated packaged substrate disposed thereon.
25. A method in accordance with claim 24 wherein (c) further comprises unloading the at least another previously singulated packaged substrate at the unloading location.
26. A method in accordance with claim 20 wherein (c) further comprises moving the first movable mount in the first reference direction.
27. A method in accordance with claim 20 wherein (c) further comprises moving the water jet in the second reference direction.

28. A method in accordance with claim 21 wherein (e) further comprises moving the second movable mount in the first reference direction.

29. A method in accordance with claim 21 wherein (e) further comprises moving the water jet in the second reference direction.

30. A method in accordance with claim 17, wherein (d) comprises picking the at least one packaged substrate off the first movable mount, moving the first movable mount from the cutting location to the loading location, moving the second movable mount from the unloading location to the cutting location, and placing the at least one packaged substrate on the second movable mount.